

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr><td>Hsiao Chuan CHANG</td><td>12/23/2008</td></tr> <tr><td>Tsung Yueh TSAI</td><td>12/23/2008</td></tr> <tr><td>Yi Shao LAI</td><td>12/23/2008</td></tr> <tr><td>Ho Ming TONG</td><td>12/23/2008</td></tr> <tr><td>Jian Cheng CHEN</td><td>12/23/2008</td></tr> <tr><td>Wei Chi YIH</td><td>12/23/2008</td></tr> <tr><td>Chang Ying HUNG</td><td>12/23/2008</td></tr> </tbody> </table>		Name	Execution Date	Hsiao Chuan CHANG	12/23/2008	Tsung Yueh TSAI	12/23/2008	Yi Shao LAI	12/23/2008	Ho Ming TONG	12/23/2008	Jian Cheng CHEN	12/23/2008	Wei Chi YIH	12/23/2008	Chang Ying HUNG	12/23/2008
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CORRESPONDENCE DATA																	
<p>Fax Number: (703)518-5499</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 7036841111</p> <p>Email: awilson@ipfirm.com</p> <p>Correspondent Name: LOWE HAUPTMAN HAM & BERNER, LLP</p> <p>Address Line 1: 1700 DIAGONAL ROAD</p> <p>Address Line 2: SUITE 300</p> <p>Address Line 4: ALEXANDRIA, VIRGINIA 22314</p>																	
ATTORNEY DOCKET NUMBER:	4459-312																

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PATENT
REEL: 022942 FRAME: 0646

NAME OF SUBMITTER:

Ayesha Wilson

Total Attachments: 1

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ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) <u>Hsiao Chuan CHANG</u>	(5) <u>Jian Cheng CHEN</u>
(2) <u>Tsung Yueh TSAI</u>	(6) <u>Wei Chi YIH</u>
(3) <u>Yi Shao LAI</u>	(7) <u>Chang Ying HUNG</u>
(4) <u>Ho Ming TONG</u>	(8) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto

Advanced Semiconductor Engineering, Inc.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

SEMICONDUCTOR PACKAGE, METHOD FOR ENHANCING THE BOND OF A BONDING WIRE, AND METHOD FOR MANUFACTURING A SEMICONDUCTOR PACKAGE

for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or

(a) for which an application for United States Letters Patent was executed on December 23, 2008,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside our signatures:

INVENTORS

DATE SIGNED

1) Signature: <u>Hsiao Chuan Chang</u>	
Name: <u>Hsiao Chuan CHANG</u>	
2) Signature: <u>Tsung Yueh Tsai</u>	
Name: <u>Tsung Yueh TSAI</u>	
3) Signature: <u>Yi Shao Lai</u>	
Name: <u>Yi Shao LAI</u>	
4) Signature: <u>Ho Ming Tong</u>	
Name: <u>Ho Ming TONG</u>	
5) Signature: <u>Jian Cheng Chen</u>	
Name: <u>Jian Cheng CHEN</u>	
6) Signature: <u>Wei Chi Yih</u>	
Name: <u>Wei Chi YIH</u>	
7) Signature: <u>Chang Ying Hung</u>	
Name: <u>Chang Ying HUNG</u>	

<u>December 23, 2008</u>
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